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- **EPIC**[™] (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC}, $T_A = 25^{\circ}C$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Ceramic (J) 300-mil DIPs

description

These hex inverters are designed for 2.7-V to 5.5-V V_{CC} operation.

The 'LVU04 contain six independent inverters with unbuffered outputs. These devices perform the Boolean function $Y = \overline{A}$.

The SN74LVU04 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVU04 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVU04 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each inverter)									
INPUT A	OUTPUT Y								
Н	L								
L	Н								



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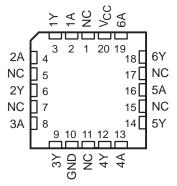
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SN54LVU04	. J OR W PACKAGE
SN74LVU04 D	, DB, OR PW PACKAGE
(ТС	OP VIEW)

	•			
1A [1Y [2A [2Y [3A] 3Y [GND]	2 3 4 5	σ	14 13 12 11 10 9 8	V _{CC} 6A 6Y 5A 5Y 4A 4Y

SN54LVU04 ... FK PACKAGE (TOP VIEW)

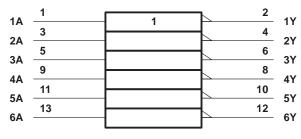


NC - No internal connection

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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, DB, J, PW and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	-0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Notes 1 and 2)	-0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_{O} (V _O = 0 to V _{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): D package	1.25 W
DB or PW package	e 0.5 W
Storage temperature range, T _{stg}	

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stressratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 7 V maximum.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 4)

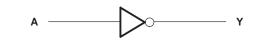
			SN54L	J04 SN74LVU04			
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	5.5	2.7	5.5	V
Maria		V _{CC} = 2.7 V to 3.6 V	2.4		2.4		N
VIH	High-level input voltage	V_{CC} = 4.5 V to 5.5 V	3.55		3.55		V
VIL		V _{CC} = 2.7 V to 3.6 V		0.5		0.5	
	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0 <	Vcc	0	VCC	V
VO	Output voltage		Ó	VCC	0	VCC	V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	200	-6		-6	
юн	High-level output current	V_{CC} = 4.5 V to 5.5 V	4	-12		-12	mA
		V _{CC} = 2.7 V to 3.6 V		6		6	
IOL	Low-level output current		12		12	mA	
$\Delta t/\Delta v$	Input transition rise or fall rate	-	0	100	0	100	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



logic diagram, each inverter (positive logic)



SN54LVU04, SN74LVU04 HEX INVERTERS

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DADAMETER	TEST CONDITIONS		TEST CONDITIONS		v +	SN	154LVUC	4	SN	74LVU0	4	
PARAMETER	IESI CO	vcc†	MIN	TYP	MAX	MIN	TYP	MAX	UNIT			
	$V_{I} = V_{IL}$	I _{OH} = – 100 μA	MIN to MAX	V _{CC} -0	.5		V _{CC} -0.	5				
VOH	$V_{I} = GND,$	I _{OH} = – 6 mA	3 V	2.4			2.4			V		
	$V_I = GND,$	I _{OH} = – 12 mA	4.5 V	3.6			3.6					
	$V_{I} = V_{IH}$	l _{OL} = 100 μA	MIN to MAX			0.5			0.5			
VOL	$V_{I} = V_{CC},$	I _{OL} = 6 mA	3 V		12	0.4			0.4	V		
	$V_{I} = V_{CC},$	I _{OL} = 12 mA	4.5 V		EL	0.55			0.55			
L.	$V_I = V_{CC}$ or GND		3.6 V		2	±1			±1	A		
Ц			5.5 V		Ś	±1			±1	μA		
			3.6 V	00	, ,	20			20			
lcc	$V_{I} = V_{CC} \text{ or } GND,$	I _O = 0	5.5 V	40		20			20	μA		
∆ICC	One input at V_{CC} – Other inputs at V_{CC}		3 V to 3.6 V			500			500	μΑ		
0	VI = V _{CC} or GND				3.3 V		7			7		- 5
Ci			5 V		7.5			7.5		pF		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

		то		~	SN54L	.VU04		4		
PARAMETER	PARAMETER FROM (INPUT)		V _{CC} =	= 5 V ± 0.5 V	Vcc =	3.3 V ±	0.3 V	Vcc=	2.7 V	UNIT
	((OUTPUT)	MIN	TYP MAX	MIN	TYP	MAX	MIN	MAX	
^t pd	А	Y		5 (10		8	13	REF	13	ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

						SN74L	.VU04					
PARAMETER	FROM (INPUT)		-	OUTPUT)	V _{CC} :	= 5 V ± 0).5 V	$V_{CC} = 3.3 V \pm 0.3 V$ $V_{CC} = 3.3 V \pm 0.3 V$			2.7 V	UNIT
	((0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX		
^t pd	A	Y		5	10		8	13		13	ns	

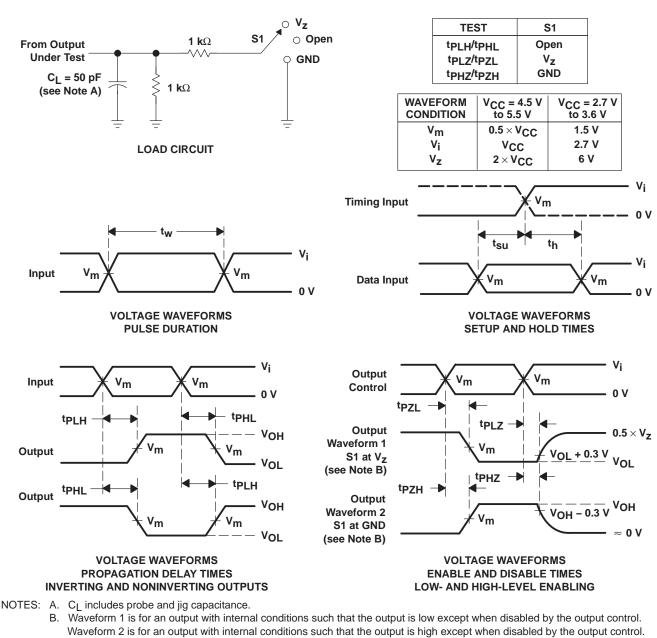
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
Cpd	Power dissipation capacitance per inverter	C ₁ = 50 pF, f = 10 MHz	3.3 V	7	٥F
Фра	Power dissipation capacitance per inventer	$G_{L} = 50 \text{pr}, I = 10 \text{MHz}$	5 V	12	рг



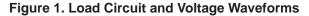
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PARAMETER MEASUREMENT INFORMATION

- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. tPLH and tPHL are the same as tpd.







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LVU04D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
SN74LVU04DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	Samples Not Available
SN74LVU04DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
SN74LVU04PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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